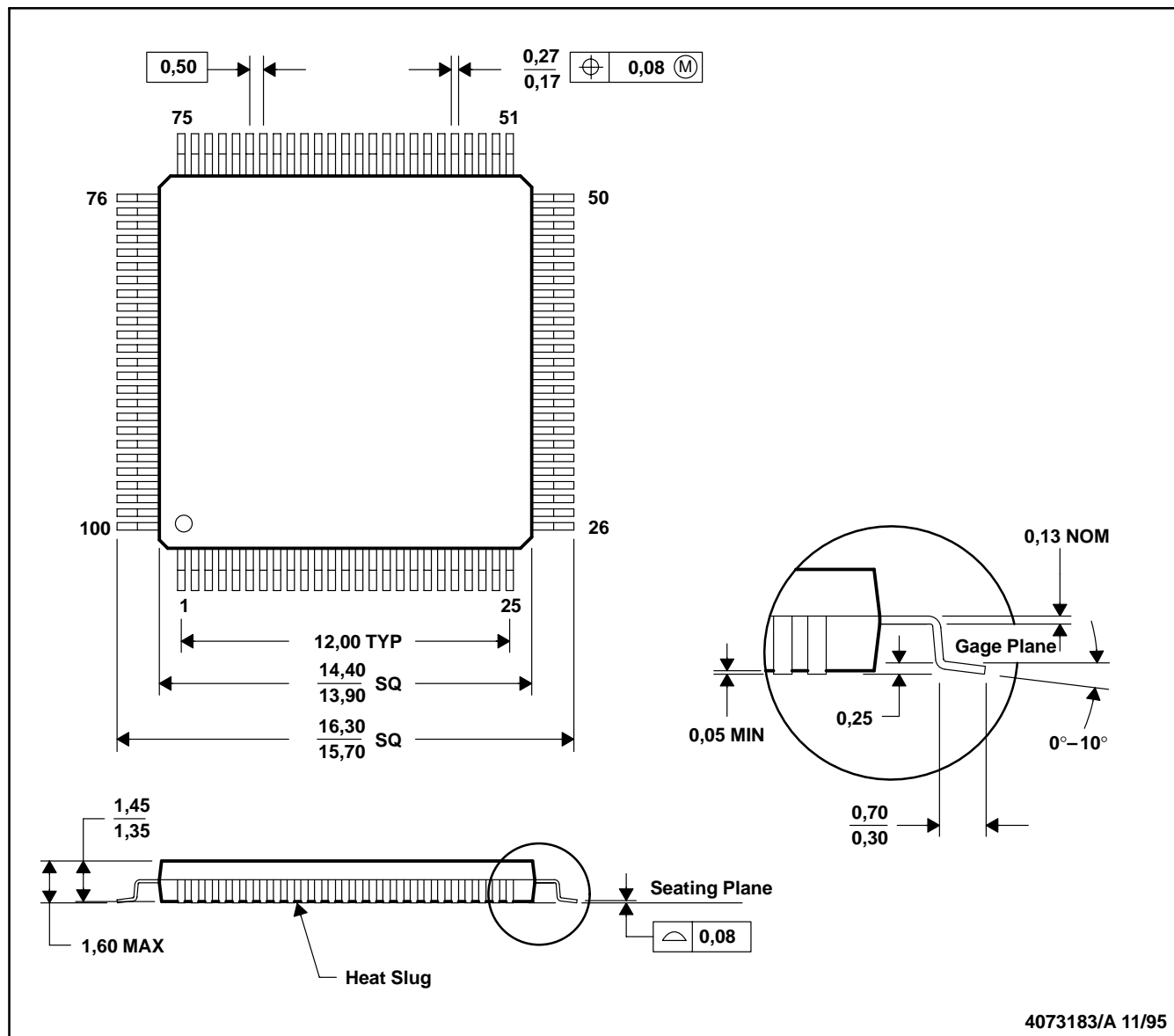


## PDK (S-PQFP-G100)

## PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Thermally enhanced molded plastic package with a heat slug (HSL)

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